

TechWatch



ECA Fall Engineering Summit

December 2009 Report

— October Savannah Summit Activity Highlights —

The main core of activities of the ECA Fall Engineering Summit was held October 5-6, 2009 in Savannah, Georgia at the DoubleTree Hotel Historic Savannah. It was followed the next week at the same facilities by a session of the CE-2.0 Connector Committee, which

of Non-IC Electronic Components. ECA has embraced the concept of working jointly with other Standards Development Organizations on issues of common interest and is working with the JEDEC Solid State Technology Association and IPC.

SAVE THE DATE—

**ECA Spring Engineering Summit
Week of 25 APRIL 2010
Orlando, Florida**

Mark your calendars, details to follow shortly.

met 13-14 October.

The meetings were a successful endeavor despite the challenges resulting from the result of a worldwide recession. Quorums were present for the meetings, and for those members who were unable to physically attend due to corporate travel restrictions or other schedule logistical challenges, ECA deployed Web Conferencing technologies including Web Cam.

The activities began on Monday, the 5th which included a Tantalum Working Group meeting and an evening welcome reception. The Working Group members typically roll up their sleeves and the session gets the document prepared for the P-2.5 Committee on Tantalum Capacitors that meets on that following Wednesday.

Tuesday began with the S-1 Committee General Session. Items discussed included the New Joint Standard J-STD-075 on Assembly Processing, Evaluation and Classification

The committee also discussed the current environmental issues and regulations as they affect reporting requirements up and down the supply chain. Of particular interest are the RoHS and REACH programs from Europe. ECA works with a number of other associations to publish the Joint Industry Guide JIG-101. It is a Standard covering Material Composition Declaration. Ed Mikoski, ECA reported that the 3rd Edition of the document is now in the draft stage, with an expected publish date in February 2010. Ed also reported that the International Electrotechnical Commission (IEC) has a Conformity Assessment Document IECQ QC080000 on Hazardous Substance Process Management (HSPM) that was originated by the US Electronic Component Certification Board (ECCB) in a document that went through the EIA/ECA standards development process and was published as EIA/ECCB-954. The contents of the document were contributed to the international group IECQ as the core draft of the QC080000 document. Subsequently the global industry currently in just the last few years has over 2000 companies certified to the environmental management process HSPM.

Also on Tuesday, ECA held a face-to-face meeting of the US Technical Advisory Group (TAG) to the international Technical Committee 40 of the IEC. TC 40's scope covers Passive Components such as Resistors and Capacitors, but also Inductors and has a Working Group WG36 that develops standards for Tape and Reel and associated Automated Handling Equipment.

The Engineering Summit participants in these subject areas will become a major



component of the Technical Advisory Group and will plan to hold meetings during the Summits. On Thursdays of the Summit meetings, the Automated Component Handling (ACH) Committee convenes and is also intending to more directly participate in the WG36 projects through the TC40 US TAG.

The US TAG to TC40 plans to review and compare the EIA/ECA standards for capacitors and resistors with those international standards published by the International Electrotechnical Commission (IEC), with consideration of back-adopting them into the US region.

Mr. Ivan Masek, CEO Novotechnik U.S., Inc. spoke at the Tuesday luncheon. As current President of the Variable Electronic Component Institute (VECI) he described the scope of the organization's products such as potentiometers and encoders. There are standards to be updated and new ones to be developed. VECI has been invited to develop those documents in the EIA/ECA ANSI –accredited standards development process, where they culminate in the recognition as American National Standards.

This week also formalized and populated the new committee P-2.7 covering EDLC Capacitors. The work here would include standardization activities of the KiloFarad International (KfI), which is Ultra Capacitors. This industry is ready for standards, and

KfI will also take advantage of the EIA/ECA standards development process. Meetings are planned

ATTENTION:

If you have not been participating in any of these activities, but would like to, please contact:

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to be in conjunction with the Spring and Fall ECA Engineering Summits.

The awards recipient at this Summit was Mr. Doug Romm of Texas Instruments. He actively chairs the ECA Soldering Technology Committee (STC) and has fostered the cooperation of the several associations that jointly work the Joint Standard J-STD-002, *“SOLDERABILITY TESTS FOR COMPONENT LEADS, TERMINATIONS, LUGS, TERMINALS AND WIRES”*.

Details on the upcoming 2010 ECA Spring Engineering Summit will be forthcoming on the ECA website,
www.ecaus.org

The following Committees are planning to meet at the ECA Spring Engineering Summit to be held the week of 25 APRIL 2010 in Orlando, Florida:

Subject	Committee	Designator
Ceramic	Ceramic Capacitors Committee	P-2
Policy	Standards Technology Policy Council	STPC
Equipment	Automated Component Handling Committee	ACH
General Session	Steering Committee General Session	S-1
Inductive Devices	Inductive Components Committee	P-3
Integrated Passives	Integrated Passive Devices Committee	P-10
International	US Tech Adv Group to IEC Technical Committee 40, Passive Components	TC 40 US TAG
Outlines	Mechanical Outlines Committee	P-4
Paper, Film, Mica	Paper, Film, Mica, & Wet Electrolytic Capacitors Committee	P-2.2
Resistors	Resistive Devices Committee	P-1
Soldering	Soldering Technology Committee	STC
Tantalum	Tantalum Capacitors Committee	P-2.5
UltraCaps, SuperCaps, EDLC's	Electrolytic Double Layer Capacitors Committee	P-2.7
Variable Components	(Tentative) VECI Standards Committee on Potentiometers and Encoders	VECI